



## Description

The HSM3113 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

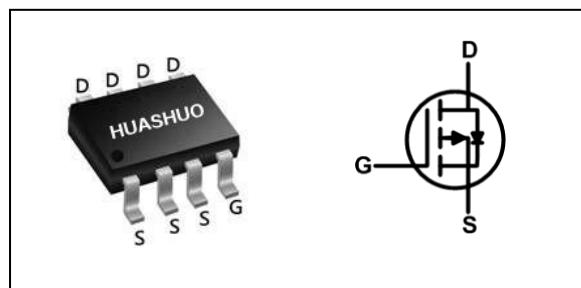
The HSM3113 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

## Product Summary

V <sub>DS</sub>	-30	V
R <sub>DS(ON),max</sub>	30	mΩ
I <sub>D</sub>	-6	A

## SOP8 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-6	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-4.7	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-24	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	45	mJ
I <sub>AS</sub>	Avalanche Current	-30	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	1.5	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	85	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	40	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=-250\mu\text{A}$	-30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $\text{I}_D=-1\text{mA}$	---	-0.022	---	$\text{V}/^\circ\text{C}$
$\text{R}_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=-10\text{V}$ , $\text{I}_D=-6\text{A}$	---	---	30	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}$ , $\text{I}_D=-3\text{A}$	---	---	55	
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_D=-250\mu\text{A}$	-1.0	---	-2.5	V
$\Delta \text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{GS}(\text{th})}$ Temperature Coefficient		---	4.6	---	$\text{mV}/^\circ\text{C}$
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-24\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\text{uA}$
		$\text{V}_{\text{DS}}=-24\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	-5	
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$\text{g}_{\text{fs}}$	Forward Transconductance	$\text{V}_{\text{DS}}=-5\text{V}$ , $\text{I}_D=-6\text{A}$	---	16	---	S
$\text{R}_g$	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	15	---	$\Omega$
$\text{Q}_g$	Total Gate Charge (-4.5V)	$\text{V}_{\text{DS}}=-20\text{V}$ , $\text{V}_{\text{GS}}=-4.5\text{V}$ , $\text{I}_D=-6\text{A}$	---	9.8	---	$\text{nC}$
$\text{Q}_{\text{gs}}$	Gate-Source Charge		---	2.2	---	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		---	3.4	---	
$\text{T}_{\text{d}(\text{on})}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=-24\text{V}$ , $\text{V}_{\text{GS}}=-10\text{V}$ , $\text{R}_g=3.3\Omega$ , $\text{I}_D=1\text{A}$	---	16.4	---	$\text{ns}$
$\text{T}_r$	Rise Time		---	20.2	---	
$\text{T}_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	55	---	
$\text{T}_f$	Fall Time		---	10	---	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=-15\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	930	---	$\text{pF}$
$\text{C}_{\text{oss}}$	Output Capacitance		---	148	---	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		---	115	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_s$	Continuous Source Current <sup>1,5</sup>	$\text{V}_G=\text{V}_D=0\text{V}$ , Force Current	---	---	-6	A
$\text{I}_{\text{SM}}$	Pulsed Source Current <sup>2,5</sup>		---	---	-24	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $\text{V}_{\text{DD}}=-25\text{V}$ ,  $\text{V}_{\text{GS}}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $\text{I}_{\text{AS}}=-30\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $\text{I}_D$  and  $\text{I}_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



### Typical Characteristics

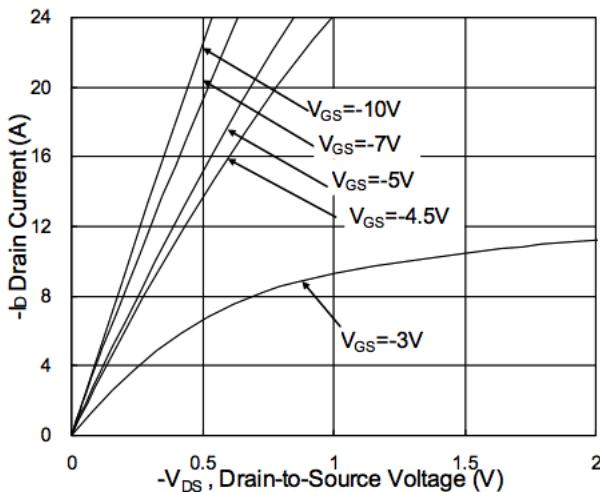


Fig.1 Typical Output Characteristics

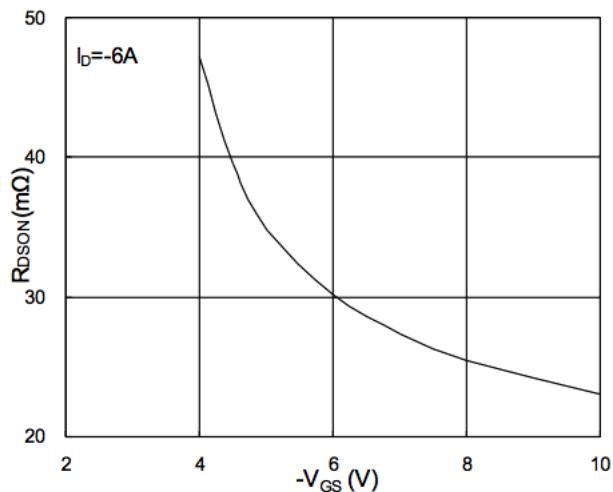


Fig.2 On-Resistance v.s Gate-Source

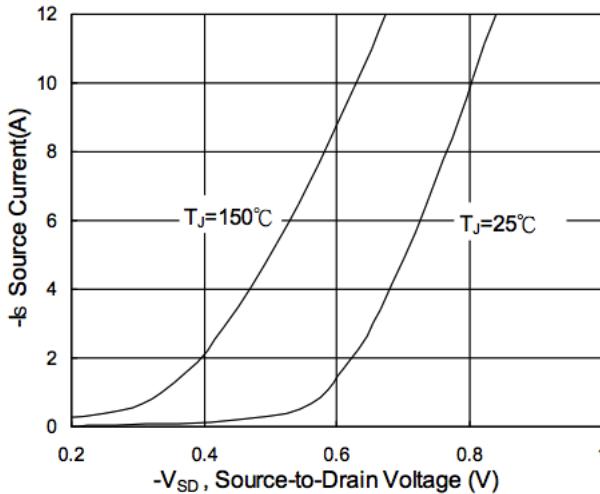


Fig.3 Forward Characteristics Of Reverse

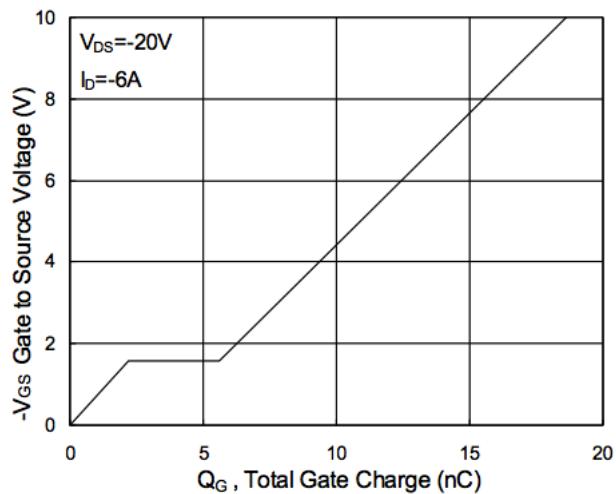


Fig.4 Gate-Charge Characteristics

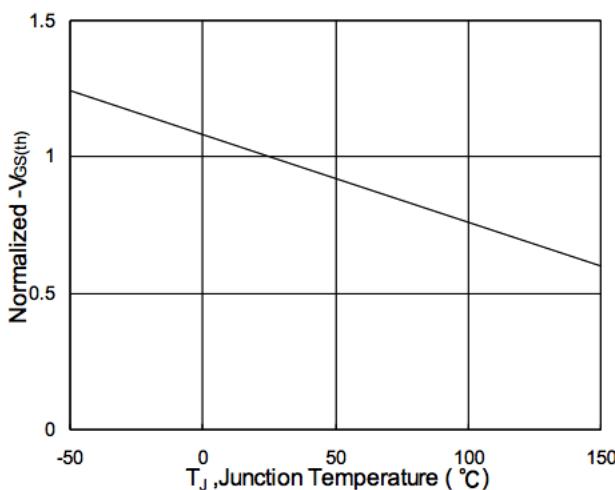


Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$

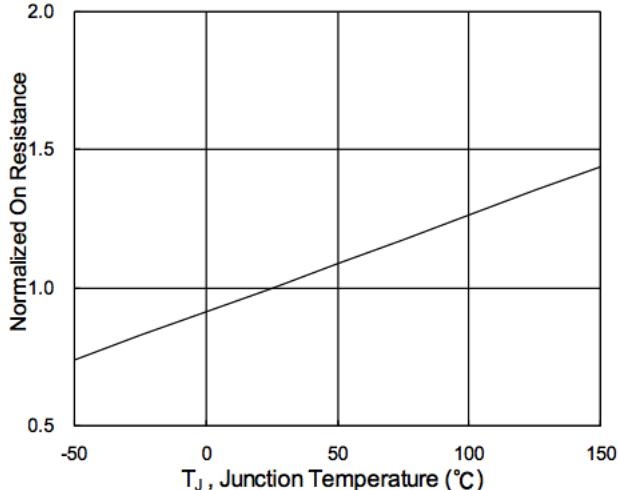


Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$



P-Ch 30V Fast Switching MOSFETs

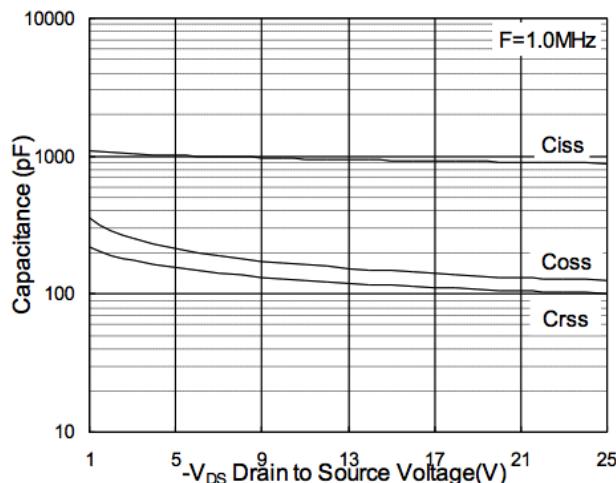


Fig.7 Capacitance

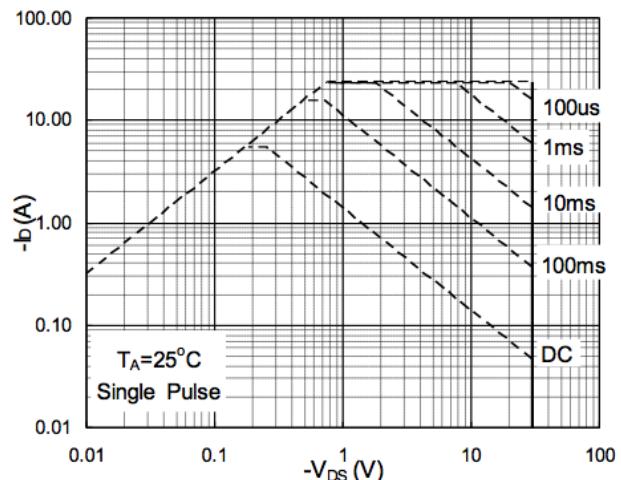


Fig.8 Safe Operating Area

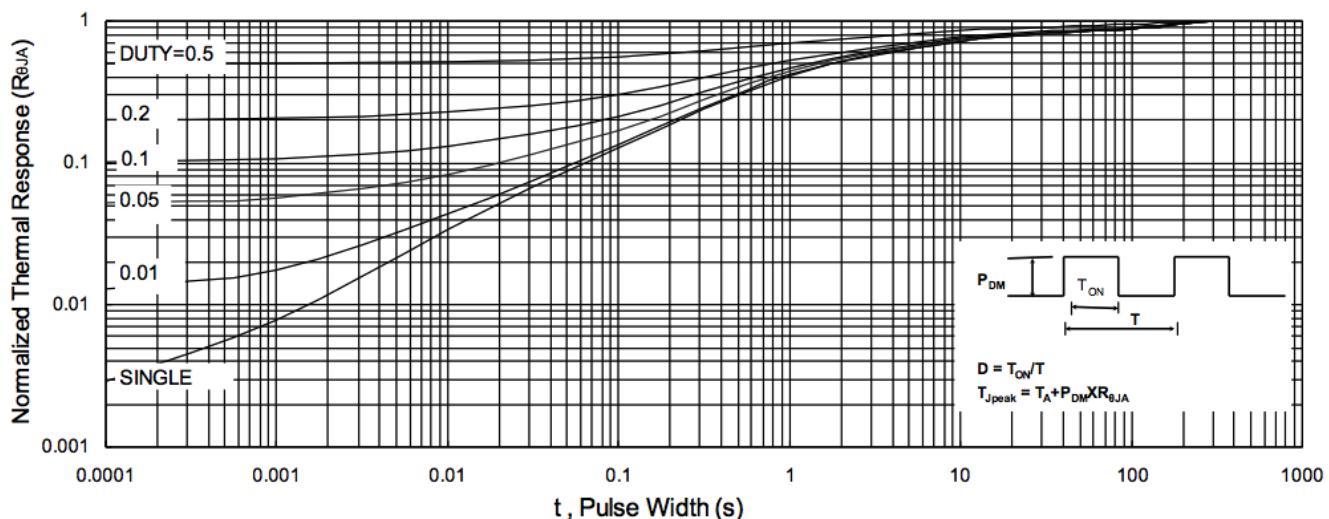


Fig.9 Normalized Maximum Transient Thermal Impedance

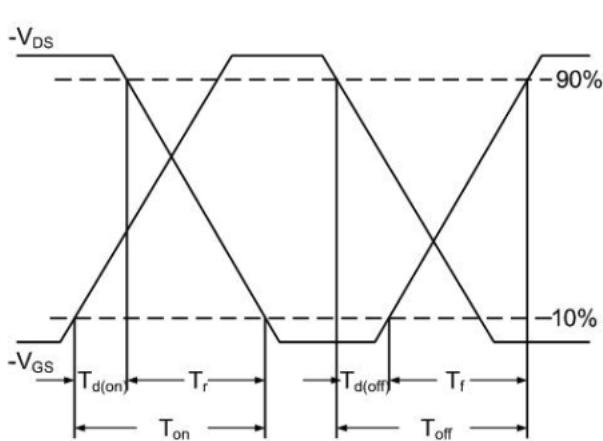


Fig.10 Switching Time Waveform

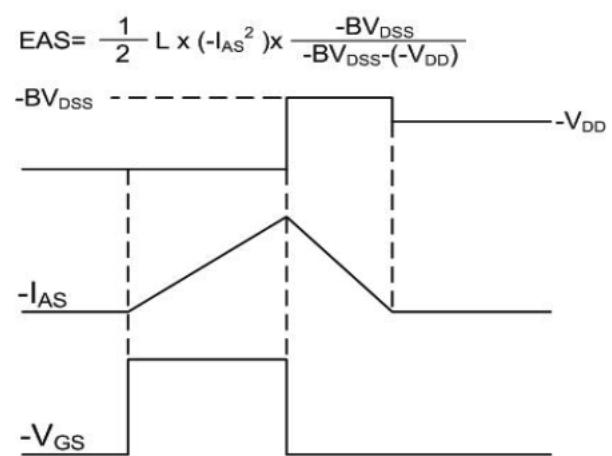


Fig.11 Unclamped Inductive Switching



## Ordering Information

Part Number	Package code	Packaging
HSM3113	SOP-8	4000/Tape&Reel

